

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT3279979

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
NAOTO HINO	03/13/2015
TAKAYUKI OCHI	03/13/2015
KOSUKE ENDO	03/13/2015
KEI YOSHINAKA	03/13/2015
MIZUHO HARA	03/13/2015
RISA WATANABE	03/13/2015
RYO NAKAGAWA	03/13/2015
KAE OKAZAWA	03/02/2015
RECEIVING PARTY DATA	
Name:	SONY CORPORATION
Street Address:	1-7-1 KONAN, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	108-0075
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14666852
CORRESPONDENCE DATA	
Fax Number:	(703)413-2220
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(703) 413-3000
Email:	zvukovic@oblon.com
Correspondent Name:	OBLON, ET AL.
Address Line 1:	1940 DUKE STREET
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	447777US8SOMC
NAME OF SUBMITTER:	ZELJKO VUKOVIC
SIGNATURE:	/Zeljko Vukovic/

DATE SIGNED:	03/24/2015
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Total Attachments: 6
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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

GENERATION OF A DIGEST VIDEO

For which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Mobile Communications, Inc., a Japanese corporation with offices at 1-8-15, Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as "ASSIGNEE SMC") is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1, Konan, Minato-ku, Tokyo 108-0075, Japan (hereinafter referenced as "ASSIGNEE SONY") is desirous of acquiring all the interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries held by ASSIGNEE SMC as the sole owner to the rights by this assignment ;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE SMC, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto; and

CONCURRENTLY HERewith in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNEE SMC by these presents do hereby assign, sell and transfer unto the said ASSIGNEE SONY, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto,

The undersigned inventor(s) and ASSIGNEE SMC hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE SONY, as the assignee of the whole right, title and interest thereto;

The undersigned inventor(s) and ASSIGNEE SMC further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE SONY or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

The undersigned inventor(s) and ASSIGNEE SMC further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

The undersigned inventor(s) and ASSIGNEE SMC further agree that ASSIGNEE SONY will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention

and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

The undersigned inventor(s) and ASSIGNEE SMC hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And we hereby authorize and request my attorney(s) of record in this application to insert the application number

Filing Date:

This assignment executed on the dates indicated below.

Naoto HINO
Name of first or sole inventor Execution date of U.S. Patent Application
Tokyo, JAPAN
Residence of first or sole inventor
Naoto Hino March 13, 2015
Signature of first or sole inventor Date of this assignment

Takayuki OCHI
Name of second inventor Execution date of U.S. Patent Application
Tokyo, JAPAN
Residence of second inventor
Takayuki Ochi March 13, 2015
Signature of second inventor Date of this assignment

Kosuke ENDO
Name of third inventor Execution date of U.S. Patent Application
Tokyo, JAPAN
Residence of third inventor
Kosuke Endo March 13, 2015
Signature of third inventor Date of this assignment

Kei YOSHINAKA
Name of fourth inventor Execution date of U.S. Patent Application
Tokyo, JAPAN
Residence of fourth inventor
Kei Yoshinaka March 13, 2015
Signature of fourth inventor Date of this assignment

Mizuho HARA

Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, JAPAN

Residence of fifth inventor

Mizuho Hara

Signature of fifth inventor

March, 13, 2015

Date of this assignment

Risa WATANABE

Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, JAPAN

Residence of sixth inventor

Risa Watanabe

Signature of sixth inventor

March, 13, 2015

Date of this assignment

Ryo NAKAGAWA

Name of seventh inventor

Execution date of U.S. Patent Application

Tokyo, JAPAN

Residence of seventh inventor

Ryo Nakagawa

Signature of seventh inventor

March, 13, 2015

Date of this assignment

Kae OKAZAWA

Name of eighth inventor

Execution date of U.S. Patent Application

Tokyo, JAPAN


Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

SONY MOBILE COMMUNICATIONS, INC.

Date: Mar. 23, 2015

By: 

Name:
Title:

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
GENERATION OF A DIGEST VIDEO

For which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

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NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE SMC, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto; and

CONCURRENTLY HERewith in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNEE SMC by these presents do hereby assign, sell and transfer unto the said ASSIGNEE SONY, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto,

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The undersigned inventor(s) and ASSIGNEE SMC further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE SONY or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

The undersigned inventor(s) and ASSIGNEE SMC further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

The undersigned inventor(s) and ASSIGNEE SMC further agree that ASSIGNEE SONY will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention

and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

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And we hereby authorize and request my attorney(s) of record in this application to insert the application number

Filing Date:

This assignment executed on the dates indicated below.

Naoto HINO
Name of first or sole inventor Execution date of U.S. Patent Application

Tokyo, JAPAN
Residence of first or sole inventor

Signature of first or sole inventor Date of this assignment

Takayuki OCHI
Name of second inventor Execution date of U.S. Patent Application

Tokyo, JAPAN
Residence of second inventor

Signature of second inventor Date of this assignment

Kosuke ENDO
Name of third inventor Execution date of U.S. Patent Application

Tokyo, JAPAN
Residence of third inventor

Signature of third inventor Date of this assignment

Kei YOSHINAKA
Name of fourth inventor Execution date of U.S. Patent Application

Tokyo, JAPAN
Residence of fourth inventor

Signature of fourth inventor Date of this assignment

Mizuho HARA

Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, JAPAN

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Risa WATANABE

Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, JAPAN

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

Kae OKAZAWA

Name of seventh inventor

Execution date of U.S. Patent Application

Tokyo, JAPAN

Residence of seventh inventor

Kae Okazawa

2015.3.2

Signature of seventh inventor

Date of this assignment

SONY MOBILE COMMUNICATIONS, INC.

Date: Mar. 23, 2015

By:

Name:

Title:

